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A compound component device including laminated first compound component layers housing first electronic components, in which the first compound component layers each include an electronic component layer, including a first main surface and a second main surface opposed to the first main surface, and a redistribution layer provided on the first main surface. At least two of the plurality of first compound component layers configure an inverted layer for which the first compound component layers are paired and formed so that the second main surfaces face each other. The electronic component layer includes the first electronic component, a first resin sealing portion to seal the first electronic component, a side wall portion that encloses the first electronic component, and electronic component layer piercing vias which pierce the side wall portion and electrically connect with the redistribution layer, and the first electronic component is directly joined to the redistribution layer.

